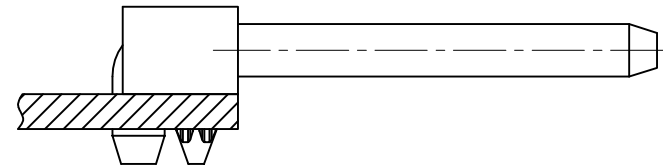
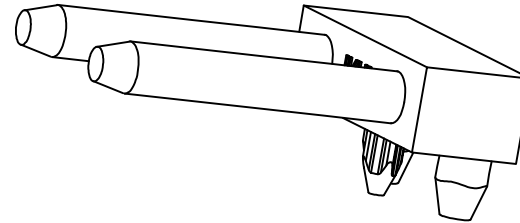
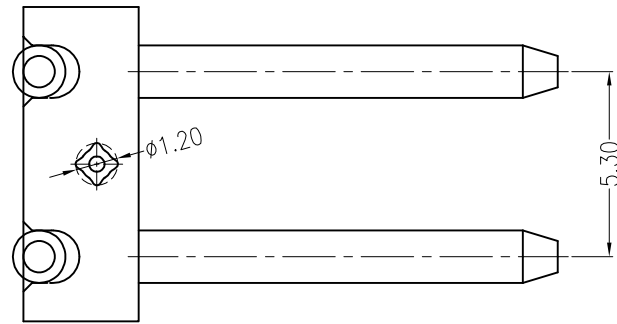
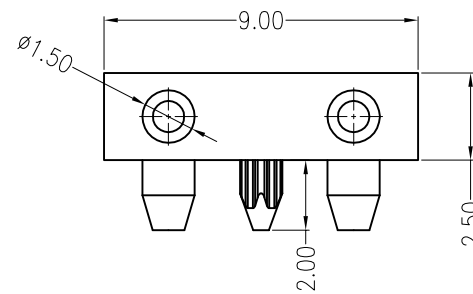
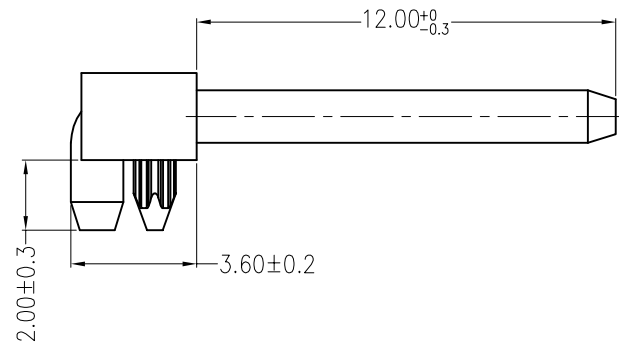
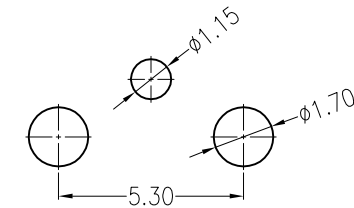


REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2017.05.08



Assembly Layout



Board Layout
General Tolerance: ± 0.05

主要技术参数 Main Specifications

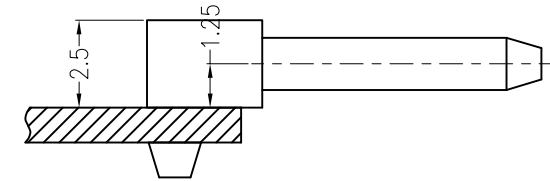
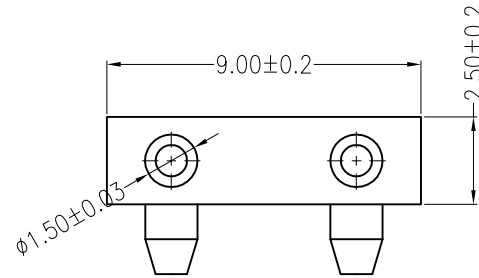
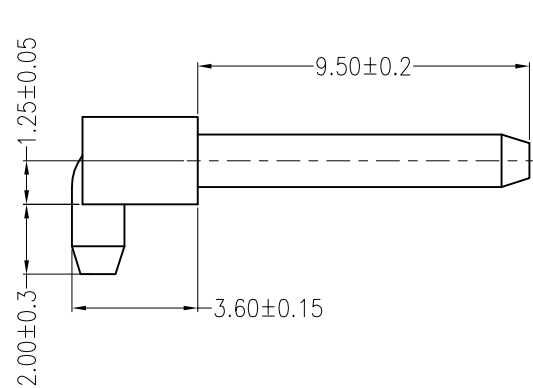
线 数 (Poles): 02
 接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$
 绝缘电阻 (Insulation resistance): $\geq 1000\text{M}\Omega$
 额定电压 (Rated voltage): 250V AC DC
 额定电流 (Rated current): 3.0A AC DC
 耐 电 压 (Withstand Voltage): 1000V AC/minute
 温度范围 (Temperature Range): $-40^{\circ}\text{C} \sim +110^{\circ}\text{C}$

ORDER INFORMATION:

L018C-02-B1MG2-P-1		SPECIAL CODE: 1=12.0*2.0 P=PE 2=Brass G=Ni
PART No.		
No. FOR CIRCUITS:		
02		
PLASTIC MATERIAL:		
B1M=PA46 (BEIGE)		

C				
B	CONTACT	2 PCS	Brass	Ni-plated
A	PEDESTAL	1 PCS	PA46	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
 东莞市高迪电子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD				
TITLE: L018C-02-1P 5.3mmPITCH 90°WAFER DIP TYPE				PART NO.: L018C-02-B1MG2-P-1
DWG NO.: GCCP-0467				SCALE 1 : 1
SHEET 1 / 1				

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	王启生	2014.12.15



Assembly Layout

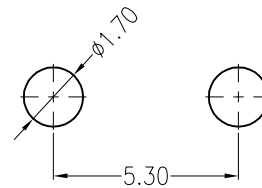
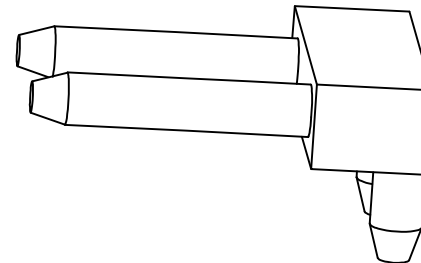
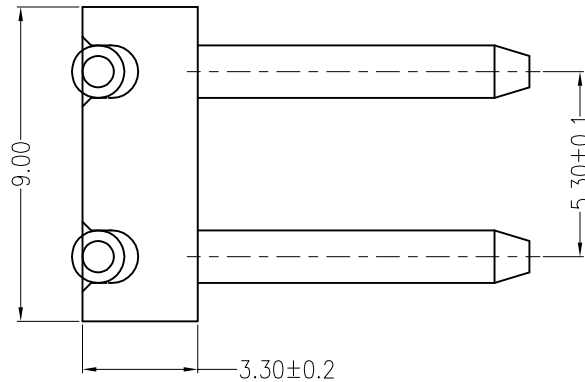
主要技术参数 Main Specifications

线 数 (Poles): 02
 接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$
 绝缘电阻 (Insulation resistance): $\geq 1000\text{M}\Omega$
 额定电压 (Rated voltage): 250V AC DC
 额定电流 (Rated current): 3.0A AC DC
 耐 电 压 (Withstand Voltage): 1000V AC/minute
 温度范围 (Temperature Range): $-40^{\circ}\text{C} \sim +110^{\circ}\text{C}$

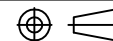
ORDER INFORMATION:

L018D-02-B3MG-P

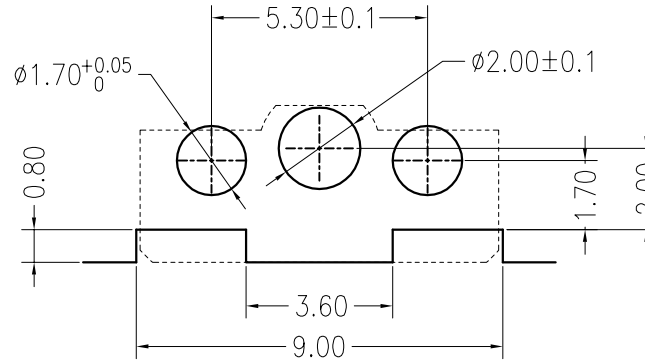
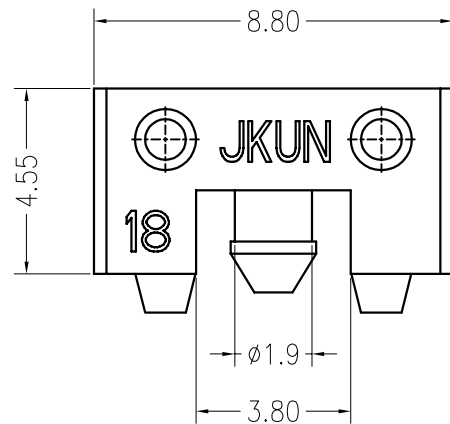
PART No. _____
 No. FOR CIRCUITS: _____
 02
 PLASTIC MATERIAL: _____
 B3M=PA46 (BEIGE)
 PACKAGING: _____
 P=PE
 PLATING: _____
 G=Ni



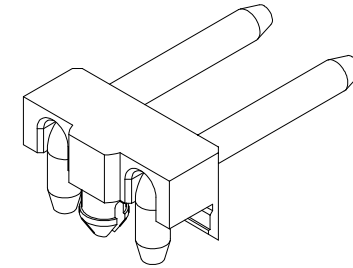
Mating PCB detail

C				
B	CONTACT	2 PCS	Brass	Ni-plated
A	PEDESTAL	1 PCS	PA46	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
 东莞市高迪电子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD				
X.±0.5	X.±5'	USE: CUSTOMER		TITLE: -
.X±0.3	.X±2'	APPD: 邵敬和		5.3mmPITCH 90°WAFER DIP TYPE
.XX±0.25	.XX±1'	CHKD: 田 峰		PART NO.: L018D-02-B3MG-P
--	--	DR: 蒋建银		DWG NO.: GCCP-0035
 UNITS: mm		SCALE 1 : 1		SHEET 1 / 1

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0	-	Release	蒋建银	2018.08.29
-	-	-	-	-



Board Layout
General Tolerance: ± 0.05



主要技术参数 Main Specifications

线 数 (Poles): 02

接触电阻 (Contact resistance): $\leq 20m\Omega$

绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$

额定电压 (Rated voltage): 250V AC DC

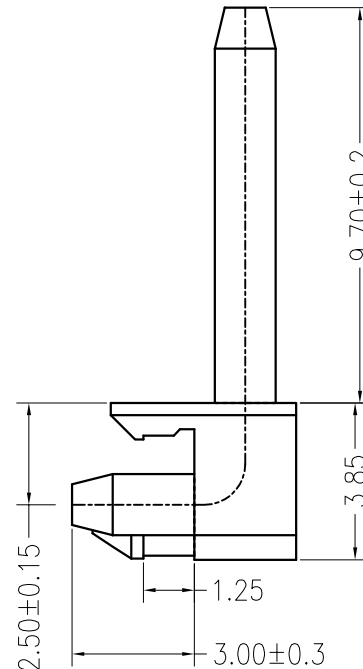
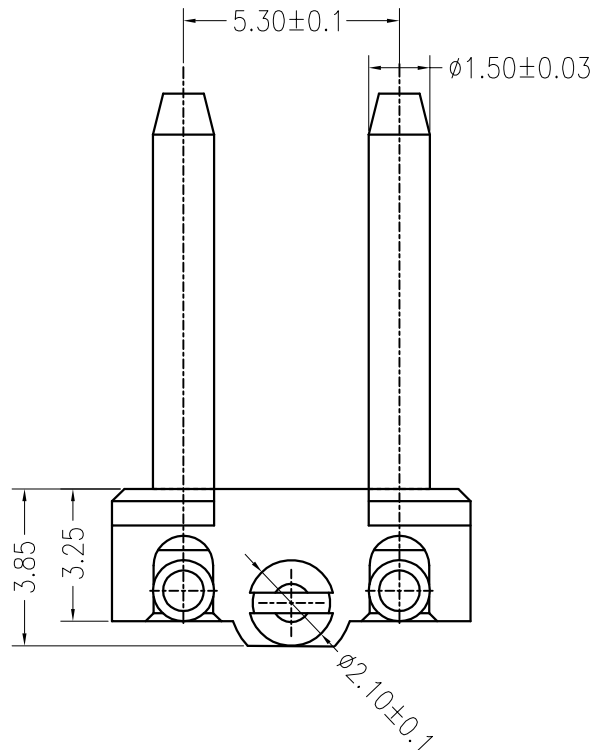
额定电流 (Rated current): 3.0A AC DC

耐 电压 (Withstand Voltage): 1000V AC/minute

温度范围 (Temperature Range): $-40^{\circ}C \sim +110^{\circ}C$

ORDER INFORMATION:

PART No.		L018E-02-B1MG2-P-1		SPECIAL CODE:
No.OF CIRCUITS:		02		弯针: 9.7*3.0
PLASTIC MATERIAL:		B1M=PA46(BEIGE)		PACKAGING:
				P=PE
				Metal code:
				2=Brass
				PLATING:
				G=Ni



C				
B	CONTACT	2 PCS	Brass	Ni-plated
A	HOUSING	1 PCS	PA46	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
东莞市高迪电子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD				TITLE: - 5.3mmPITCH 90°WAFER DIP TYPE
X.±0.5	X.±5°	USE:		PART NO.:
.X±0.3	.X±2°	CUSTOMER		L018E-02-B1MG2-P-1
.XX±0.25	.XX±1°	APPD:		DWG NO.:
--	--	邵敬和		GCCP-1207
		CHKD:		SCALE
		田峰		1 : 1
		DR:		SHEET
		蒋建银		1 / 1